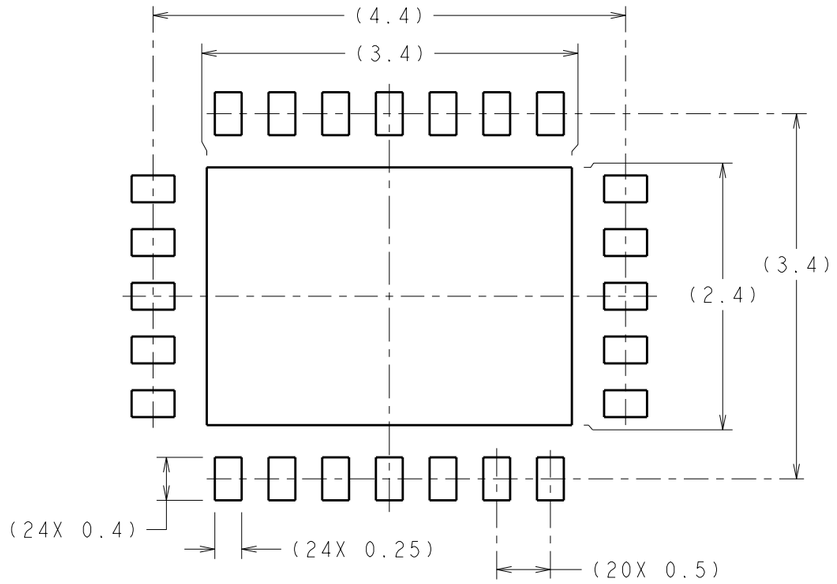
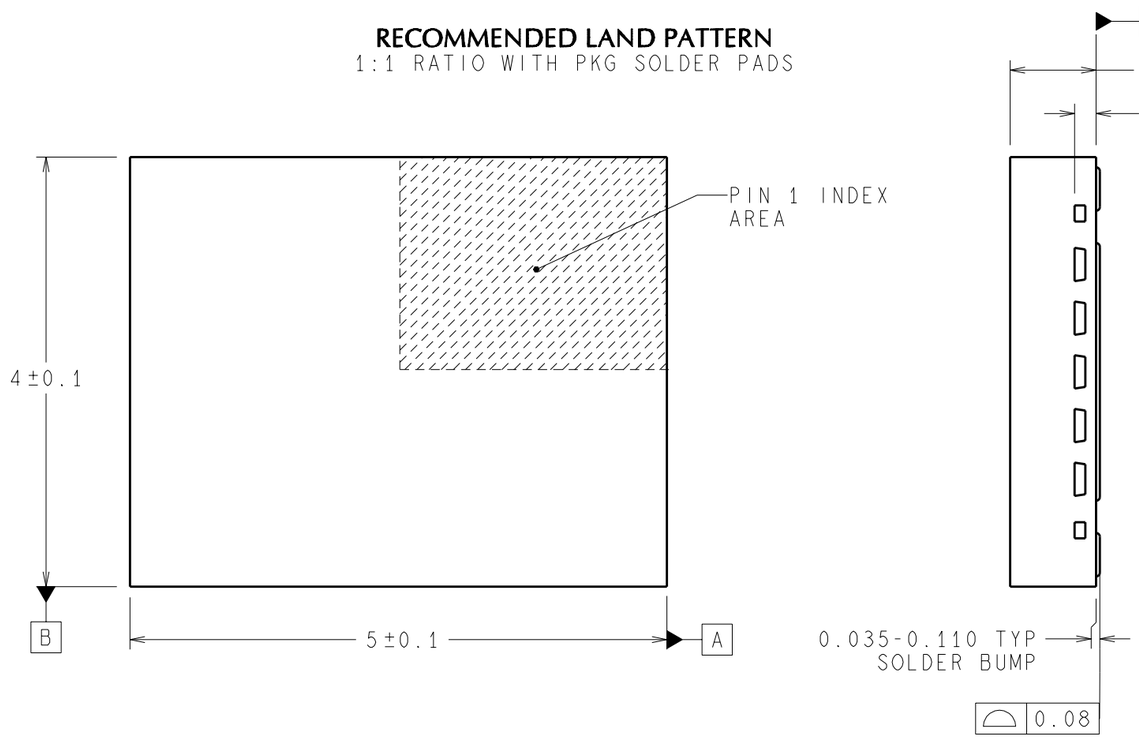
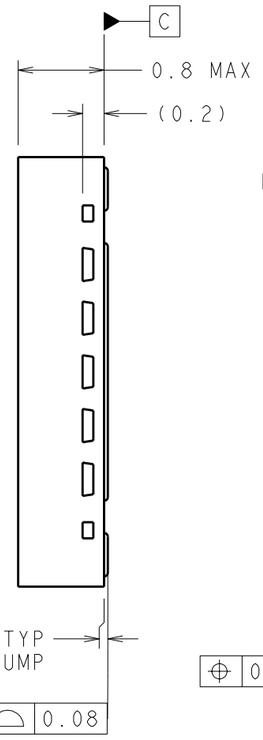
| REVISIONS | | | | |
|---|---|---|---|---|
| REV | DESCRIPTION | E.C.N. | DATE | BY/APP'D |
| A | RELEASE TO DOCUMENT CONTROL | 1246 | 11/07/2003 | AS/TL/SN |
| B | MAX SOLDER BUMP HEIGHT: 0.110 WAS 0.090; ADD BUMP COPLANARITY | 1839 | 06/24/2005 | TL/JS |

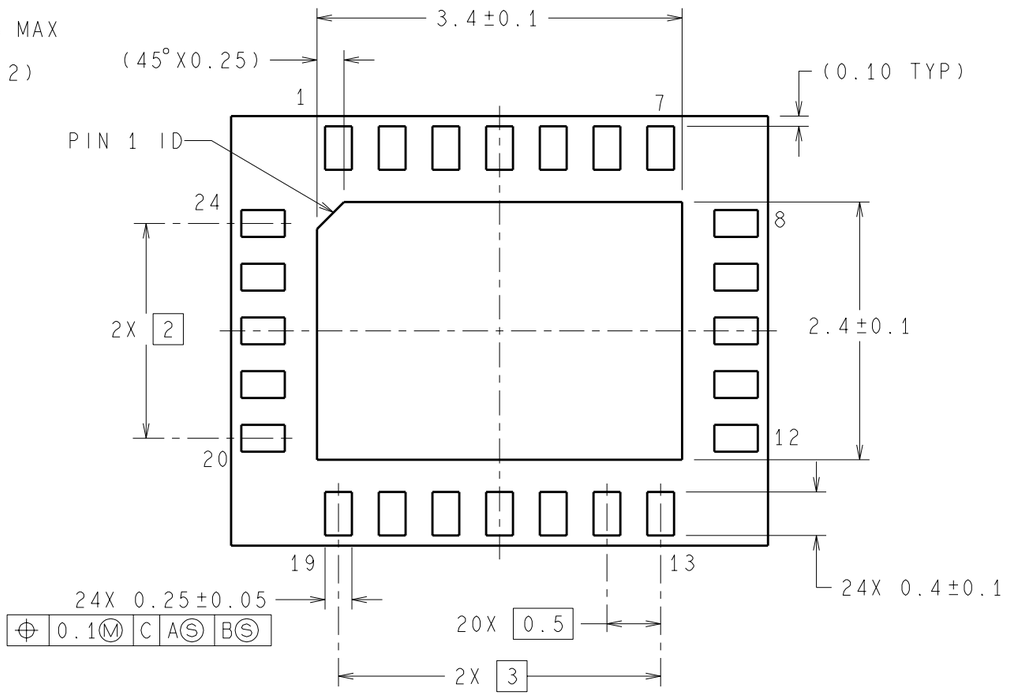



**RECOMMENDED LAND PATTERN**
1:1 RATIO WITH PKG SOLDER PADS

**DIMENSIONS ARE IN MILLIMETERS**
DIMENSIONS IN () FOR REFERENCE ONLY




NOTES: UNLESS OTHERWISE SPECIFIED.

1. FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. NO JEDEC REGRISTRATION AS OF JUNE 2005.

| APPROVALS | DATE |
|---|---|
| DRAWN: ASNOR SULAIMAN | 11/07/2003 |
| DFTG. CHK.: KURT SINCERBOX | 06/24/2005 |
| ENGR. CHK.: JEFF SCHAEFER | 06/24/2005 |

PROJECTION: MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, QUAD,
5x4X0.8mm, 24 LD,
0.5mm PITCH, SOLDER BUMP

| SCALE | SIZE | DRAWING NUMBER | REV |
|---|---|---|---|
| NTS | B | (SC)MKT-YQA24A | B |

FORMERLY: N/A

SHEET 1 of 1